

CLEAN VERSION OF THE AMENDED SPECIFICATION
AND THE AMENDED AND/OR ADDED CLAIMS

IN THE SPECIFICATION:

At page 11, line 15, through page 12, line 3, the following paragraph has been substituted for the initially filed paragraph:

Diode 20a is connected to an electrical or power source 28a, i.e., a source of current, through contact point 28. Diode 20b is connected to a ground 30a through contact point 30. Contact pad 18 and diodes 20a and 20b are each connected to component 24 which in turn typically is connected to other components 24 of die 16. The orientation of diodes 20a and 20b ensures, under typical operating conditions, that the voltage at component 24 is within the range of ground (zero volts) and the voltage of the outside power source 28a, also called Vcc. If the voltage at contact pad 18, or component 24, is greater than the voltage of power source 28, diode 20a biases the current, i.e., allows the current to flow through diode 20a toward source 28, to lower the voltage at the contact pad to that of the voltage of power source 28. If the voltage at contact pad 18, or at component 24, is less than ground, i.e., a negative voltage, diode 20b biases the current, i.e., allows the current to flow through

diode 20b toward contact pad 18, to increase the voltage at the contact pad to that of a zero voltage.

At page , line 20, through page 22, line 2, the following paragraph has been substituted for the initially filed paragraph:

Heating device 80 may comprise a resistive heating coil 80a (a section thereof being shown), a ceramic heater, a moving gas or liquid heat exchanger system, or any other heating device sufficient for purposes of the present invention. Heating device 80 typically is in direct contact with aluminum plate 102 so as to allow direct heat conduction to the wafer through plate 102 from device 80.

At page 37, the following Abstract has been substituted for the initially filed Abstract:

An apparatus includes multiple light sources that are applied to specific locations on the surface of a wafer for the purpose of causing a component on a die to respond as if a digital signal had been applied to the component. The multiple light sources may include several thousand point light sources such as the individual fibers of a fiber optic bundle. The light is

controlled in such a manner to stimulate operation of the
electronic circuit for the purpose of burning in the circuit.